Fairchild Semiconductor Product Package Material Disclosure

Package Type	**LL-34**					
Weight of Package (grams)	**Maximum** **Mininum**	**0.2645** **0.3110**				
Component	Material	Weight in grams	Substance in material	Wt% in finished product min	Wt% in finished product max	CAS#
Terminal	Fe /Ni/ Cu Alloy(Trace Element)	0.008-0095	Fe/Cu Alloy	55.6%	66%	7439-89-6/ 7440-02-0/ 7440-50-8
Glass Sleeves	PbO/ SiO_2 / K_2O/ B2O3 Alloy(Trace Element)	0.01-0.115	PbO/ SiO_2 / K_2O/ B2O3 Alloy(Trace Element)	34.75%	39.97%	1317-36-8/ 7631-86-9/ 12136-45-7 1303-86-2
Plating	Pure Tin	0.00055-0.00065	Sn	1.9%	2.26%	7440-31-5
Marking Ink	Carbon Black/ Formaldehyde /Phenol/ Triethylene glycol monomethyl ether	0.00003	Carbon Black/ Formaldehyde /Phenol/ Triethylene glycol/ monomethyl ether	0.001%	0.00011%	7440-44-0/ 50-00-0/ 108-95-2/ 112-35-6

FAIRCHILD SEMICONDUCTOR™

Materials Disclosure Disclaimer

The information provided in this Materials Disclosure is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company. Also, there may not be information included in this statement regarding the minute amounts of dopant and metal materials contained within the electrically active or passive devices contained within the finished product.